Application No.: 09/497,508 Docket No.: 8733.213.00

AMENDMENTS TO THE CLAIMS

1-8. (Canceled).

- 9. (Currently Amended) A polycrystalline silicon film on a substrate, the polycrystalline film containing metal of which density ranges $2x10^{17}$ to $5x10^{19}$ atoms/cm³, and an electrical conductivity activation energy between 0.52eV and 0.71eV, the polycrystalline silicon film comprising a uniform distribution plurality of needle-shaped silicon crystallites, wherein the polycrystalline silicon film is formed by crystallizing an amorphous silicon film containing the metal by a thermal treatment and applying an electric field.
- 10. (Previously Presented) The polycrystalline silicon film according to claim 9, wherein the metal includes one of nickel (Ni), gold (Au) and cobalt (Co).
- 11. (Previously Presented) The polycrystalline silicon film according to claim 9, wherein the metal works as a catalyst during the crystallization.
- 12. (Previously Presented) The polycrystalline silicon film according to claim 9, further comprising a buffer layer between the substrate and the polycrystalline silicon film.
- 13. (Previously Presented) The polycrystalline silicon film according to claim 10, wherein the needle-shaped silicon crystallites are formed by movement of a silicide of the metal.
- 14. (Withdrawn) A method for forming a polycrystalline silicon layer, comprising: preparing a substrate having an amorphous silicon layer;

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adding a plurality of metal atoms to the amorphous silicon layer; and

applying a heat and an electric field to the amorphous silicon layer so as to crystallize the amorphous silicon layer into a polycrystalline silicon layer using a MIC (Metal Induced Crystallization) method, the polycrystalline silicon layer including a plurality of needle-shaped silicon crystallites,

wherein the polycrystalline silicon layer has the metal atoms in the range of $2x10^{17}$ to $5x10^{19}$ atoms/cm³ and an electrical conductivity activation energy between 0.52eV and 0.71eV.

- 15. (Withdrawn) The method according to claim 14, wherein a buffer layer is formed between the substrate and the polycrystalline silicon layer.
- 16. (Withdrawn) The method according to claim 14, wherein the metal atoms includes one of nickel (Ni), gold (Au) and cobalt (Co).
- 17. (Withdrawn) The method according to claim 14, wherein the metal atoms works as a catalyst for the MIC.
- 18. (Withdrawn) The method according to claim 16, wherein a temperature range of the heat is between 400 and 500 °C.
- 19. (Withdrawn) The method according to claim 14, wherein the needle-shaped silicon crystallites are formed by movement of nickel silicide (NiSi₂).